XL-DZ504UGD/1 技术数据表

F5MM 绿发绿单孔灯座

特点（ ）：

:6.2*6.2*14.mm

Appearance dimension : 6.2*6.2*14mm

: /

Luminous color and colloid: green Light /green colloid

ROHS

Environmental protection products meet ROHS requirements

* MSL :2

Moisture sensitivity level MSL : 2 levels

EIA

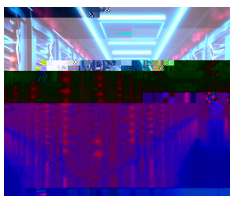
EIA standard packaging

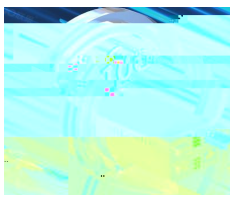
Long operating life

Reduced maintenance costs

High energy efficiency, fast startup

应用领域（product application）





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电性参数

Max Power Dissipation	PD	75	mW
Max Continuous Forward Current	IF	20	mA
Peak Forward Current	IFP	80	mA
Max Reverse Voltage	VR	5	V
Antistatic ability	ESD	2000	V
Operating Temperature Range	TOPR	-40 ~ +85	
Storage Temperature Range	TSTR	-40 ~ +85	
/ Lead Soldering Temperature/Time	TSOL	260 Ò6S	/S

Luminous Intensity	Iv	/	5000	/	mcd	IF=20mA
Dominant Wave Length	∂d	515	/	530	nm	IF=20mA
Peak Wave Length	∂p	/	525	/	nm	IF=20mA
Forward IJa∂ge i						

亮度分档

：

代码	[illegible]	最大值	单位	测试条件
B7	4000	5000	mcd	IF=20mA
B8	5000	6000		
B9	6000	8000		

亮度误差±10%　Brightness error ± 10%

电压分档

：

代码	最小值	最大值	[illegible]	测试条件
N13-2	2.6	2.8	V	IF=20mA
N13-3	2.8	3.0		
N13-4	3.0	3.2		
N13-5	3.2	3.4		

电压误差±0.1V　Voltage error ± 0.1V

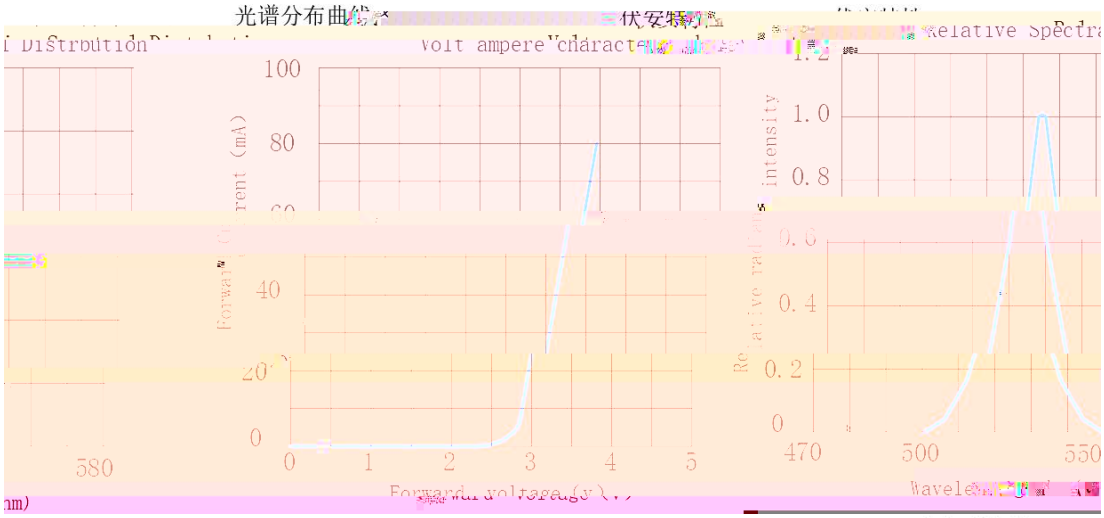
[illegible]

：

代码	最小值	最大值	单位	测试条件
HG02	515	520	nm	IF=20mA
HG03	520	525		
HG04	525	530		

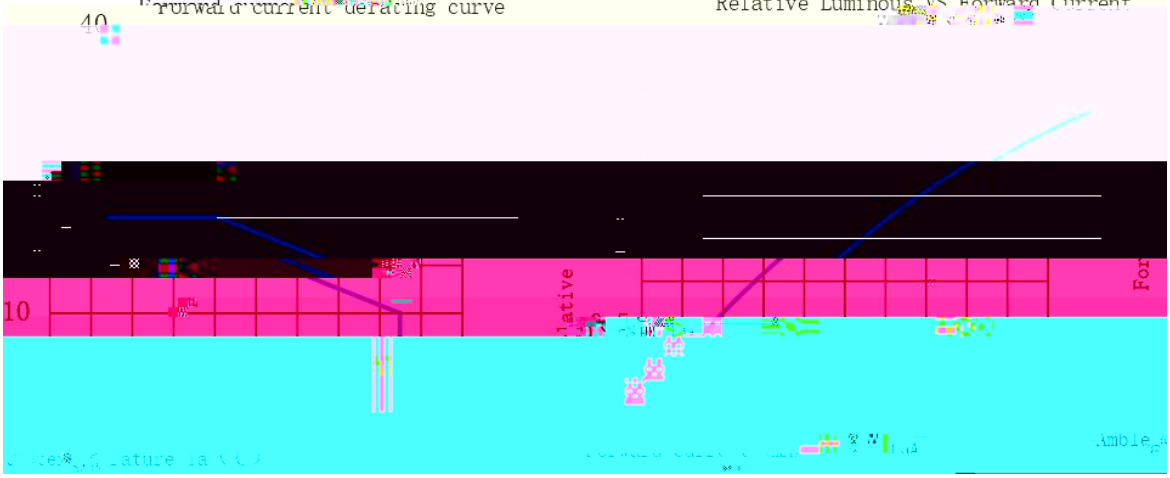
波长误差±1nm　Wavelength error ± 1nm

典型特性曲线



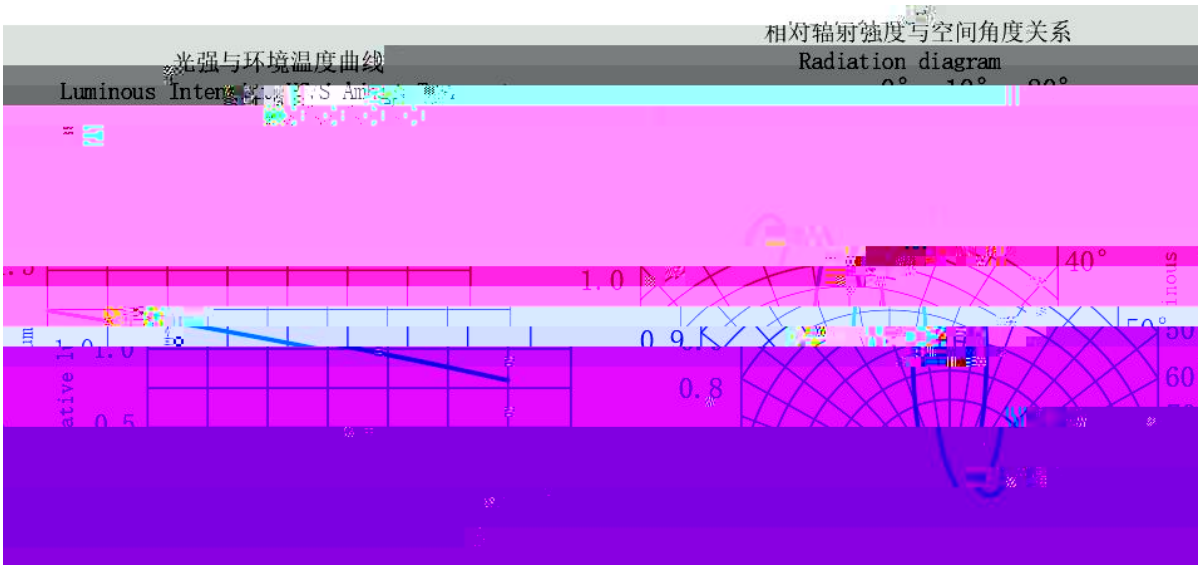
正向电流降额曲线
Forward current derating curve

相对光强与正向电流特性
Relative Luminous VS Forward Current



光强与环境温度曲线

相对辐射强度与空间角度关系
Radiation diagram



: 25 + 5 C./Note: If not otherwise indicated, the test environment temperature is 25 + 5 C.

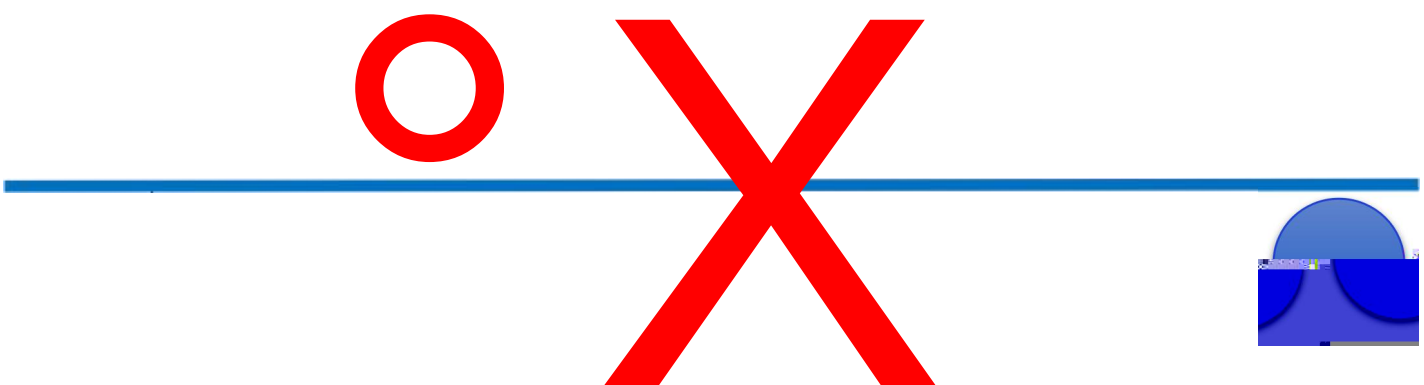
XINGLIGHT®

Part No.:XL-[illegible]

可靠性试验

Reliability Test Items And Conditions

Class	Test item	Testing environment	Testing time	Qty	Fail qty



包装

使用注意事项（ ）

1、贮存:

Storage environment of LED with temperature not exceeding 30 and relative humidity not exceeding 70%.It is recommended that LDE be used in the original box for no more than three months. If longer storage time is required, put it in the drying box and add desiccant or filled with nitrogen.

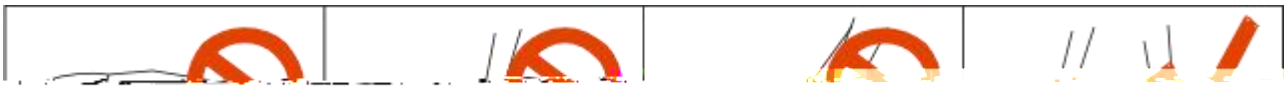
2、静电:

Part

使用注意事项（ ）

4、其他事项：

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

5、眼睛保护忠告：

LED LED

Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity, will cause great hazard to human eyes. Please be careful.

If there are any modifications to the specification sheet, no further notice will be given